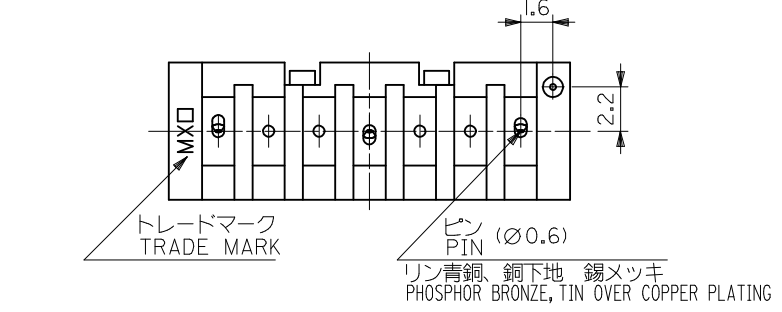
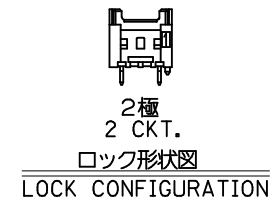
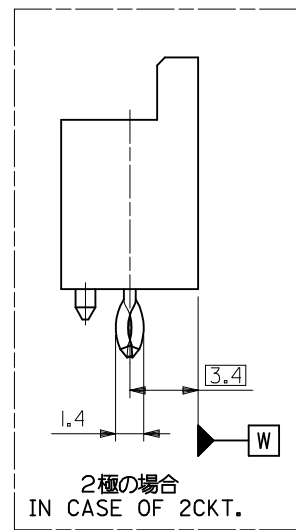
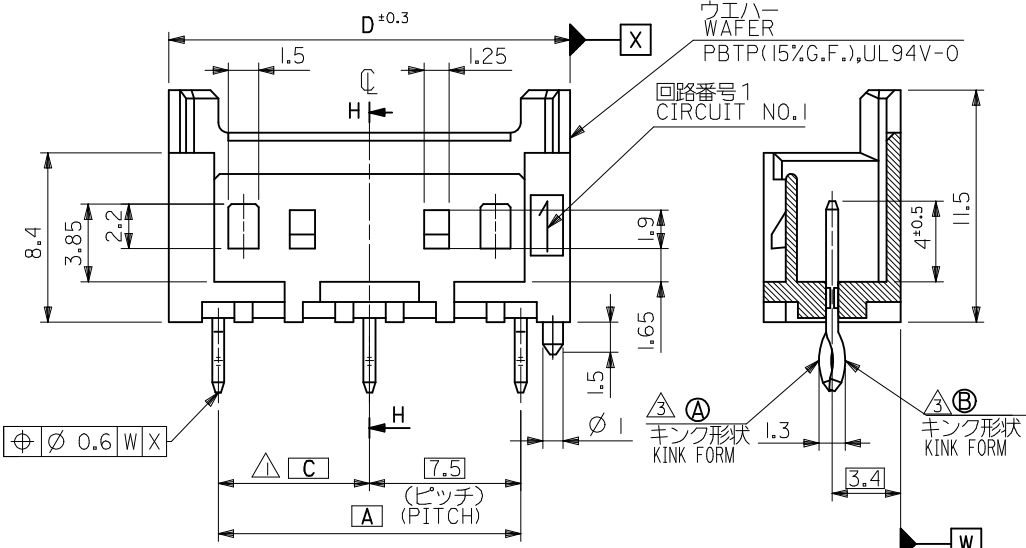


**注記 NOTES**

△ ウエハーの  $\varnothing$  から隣接するピンの  $\varnothing$  までの位置を示す。  
 SHOW POSITION FROM  $\varnothing$  OF WAFER TO  $\varnothing$  OF ADJACENT PIN.

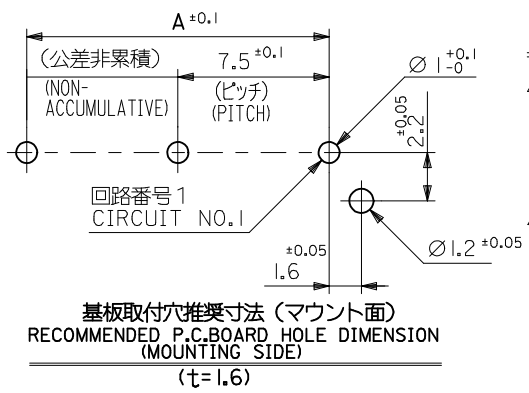
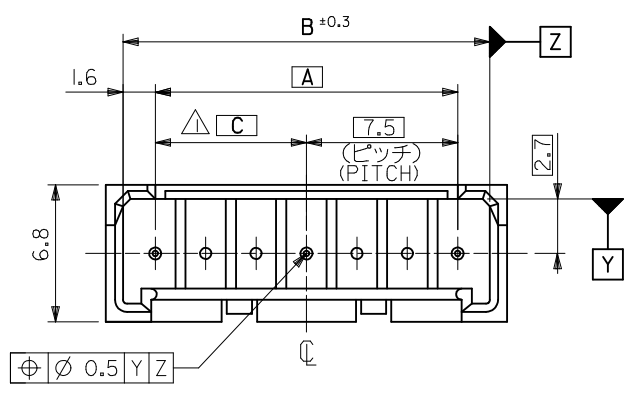
2. 嵌合相手：51102, 51103 シリーズ  
 MATES WITH : 51102, 51103 SERIES.

△ 3極以上のキンク形状は両サイドが (A)、その他の極はすべて (B) 形状とする。  
 KINK FORM MORE THAN 2 CURCUIT:  
 PINS AT BOTH ENDS ARE KINK FORMED TO (A), THE OTHER PINS ARE KINK FORMED TO (B).



RED	19.9	7.5	18.2	15	53388-0312	3
	34.9	7.5	33.2	30	53388-0510	5
NATURAL	27.4	3.75	25.7	22.5	53388-0410	4
	19.9	7.5	18.2	15	53388-0310	3
COLOR	D	C	B	A	MATERIAL NO.	極数 NO. OF CKTS.

REVISED EC NO: J2017-0525 DRWN: SAT002 CHK: DAIDA APPR: KANEKO 2017/04/13 2017/04/13 2017/04/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4.0	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±	DRAWN BY K. TOJO	DATE 1992/12/22	TITLE 7.5 WIRE TO BOARD CONN. WAFER ASSY -LEAD FREE-	
	0.25 OVER	0.5 UNDER	±	CHECKED BY H. HIRAMOTO	DATE 1993/07/16		
	0.5 OVER	1.0 UNDER	±	APPROVED BY	DATE		
	1.0 OVER	10 UNDER	±0.2	MATERIAL NO.		DOCUMENT NO.	SHEET NO.
10 OVER	30 UNDER	±0.25	SEE CHART		SD-53388-**10	1 OF 1	
30 OVER		±0.3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
ANGULAR		±3 °	SIZE A3				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							

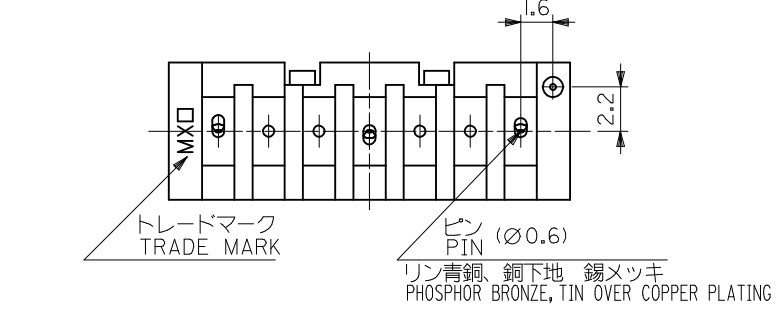
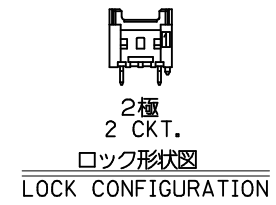
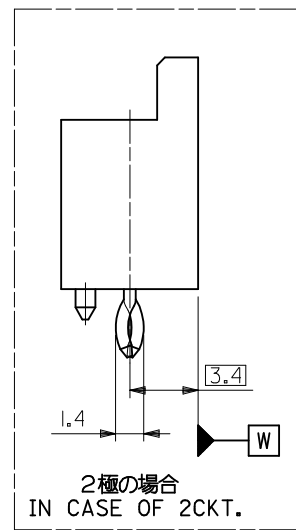
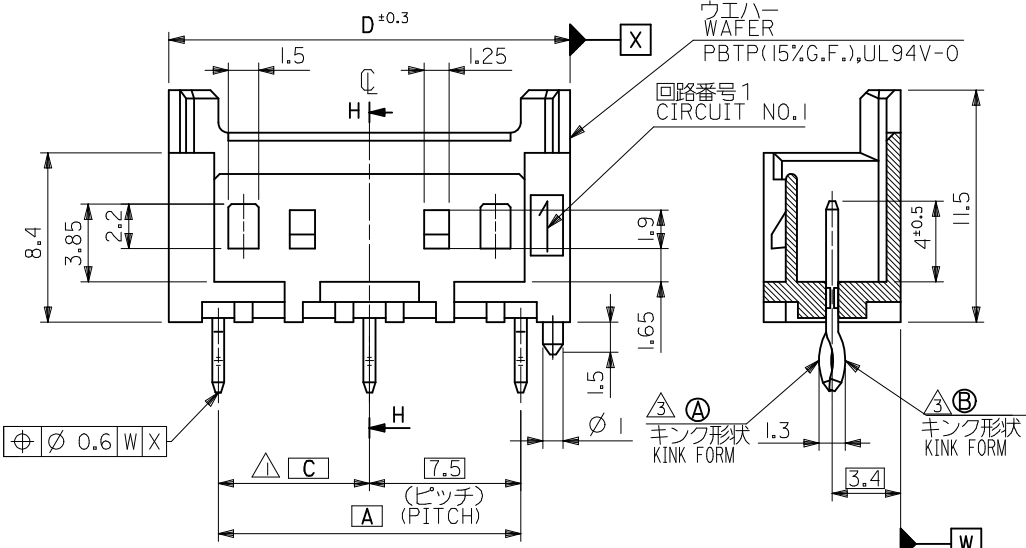


**注記 NOTES**

△ ウエハーの  $\phi$  から隣接するピンの  $\phi$  までの位置を示す。  
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2. 嵌合相手 : 51102, 51103 シリーズ  
MATES WITH : 51102, 51103 SERIES.

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REVISED EC NO: J2017-0525 DRWN: SAT002 2017/04/13 CHKD: AIDA 2017/04/13 APPR: KANEKO 2017/04/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4.0	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±	DRAWN BY K. TOJO	DATE 1992/12/22	TITLE 7.5 WIRE TO BOARD CONN. WAFER ASSY -LEAD FREE-	
	0.25 OVER	0.5 UNDER	±	CHECKED BY H. HIRAMOTO	DATE 1993/07/16		
	0.5 OVER	1.0 UNDER	±	APPROVED BY	DATE		
	1.0 OVER	10 UNDER	± 0.2	MATERIAL NO.		DOCUMENT NO.	SHEET NO.
10 OVER	30 UNDER	± 0.25	SEE CHART		SD-53388-**10	1 OF 1	
30 OVER		± 0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
ANGULAR	± 3 °		SIZE A3				